

Title (en)
POLYAMIDE COMPOSITION

Title (de)
POLYAMIDZUSAMMENSETZUNG

Title (fr)
COMPOSITION POLYAMIDE

Publication
EP 4225831 A1 20230816 (FR)

Application
EP 21801156 A 20211006

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Abstract (en)
[origin: WO2022074331A1] The present invention relates to a polyamide, a composition comprising said polyamide, the use thereof, and a moulded article derived from same and its production method. The polyamide is the result of polycondensation of an acid component and an amine component, wherein the acid component comprises, per mole of acid component, from 25 to 50 mole % of at least one fatty acid dimer; from 46 to 70 mole % of at least one aliphatic diacid; and from 0 to 11 mole % of at least one chain limiting agent; and wherein the amine component comprises, per mole of amine component, from 13 to 29 mole % of at least one aliphatic diamine; and from 66 to 82 mole % of at least one cycloaliphatic diamine. The polyamide is particularly suitable for use as a hot-melt adhesive for the low-pressure and low-temperature overmoulding of a heat-sensitive battery, for example a lithium-polymer battery.

IPC 8 full level
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